

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0876232115](#)

**Status:** **Active**

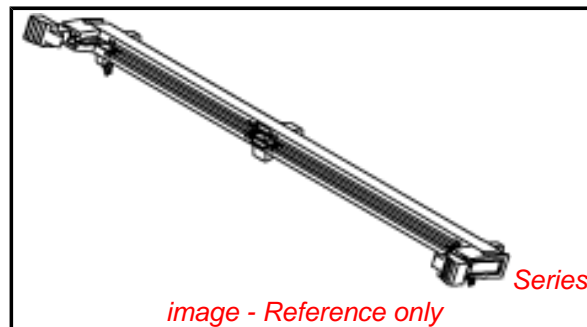
**Description:** 1.27mm (.050") Pitch DDR DIMM Socket, Low Profile (25°), Single Key, with Beveled Metal Pins and Plastic Pegs, 3.18mm (.125") Tail Length, with 3.18mm (.125") Locating Pegs, 0.76µm (30µ") Gold (Au) Plating, 184 Circuits, Leadfree

**Documents:**

[3D Model](#)

[Drawing \(PDF\)](#)

[RoHS Certificate of Compliance \(PDF\)](#)



**General**

Product Family	Memory Module Sockets
Series	<a href="#">87623</a>
Component Type	Memory Module
JEDEC Outline	MO-206
Product Name	DDR DIMM

**Physical**

Circuits (Loaded)	184
Color - Resin	Black, Natural
Durability (mating cycles max)	25
Entry Angle	25° Angle
Keying to Mating Part	Yes
Material - Metal	Brass, Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
PC Tail Length (in)	0.125 In
PC Tail Length (mm)	3.18 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.062 In
PCB Thickness Recommended (mm)	1.60 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.050 In
Pitch - Mating Interface (mm)	1.27 mm
Plating min: Mating (µin)	30.4
Plating min: Mating (µm)	0.76
Plating min: Termination (µin)	101.6
Plating min: Termination (µm)	2.54
Temperature Range - Operating	-40°C to +85°C
Termination Interface: Style	Through Hole

**Electrical**

Current - Maximum per Contact	1A
Voltage - Maximum	50V
Voltage Key	2.5V, Left

**Solder Process Data**

Duration at Max. Process Temperature (seconds)	10
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	2
Process Temperature max. C	260

**Material Info**

**Reference - Drawing Numbers**

**EU RoHS**

**ELV and RoHS  
Compliant**

**REACH SVHC**

Not Reviewed

**Halogen-Free**

**Status**

**Not Reviewed**

**China RoHS**



**Need more information on product  
environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
For a multiple part number RoHS Certificate of  
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any  
non-product compliance questions.

**Search Parts in this Series**

[87623Series](#)

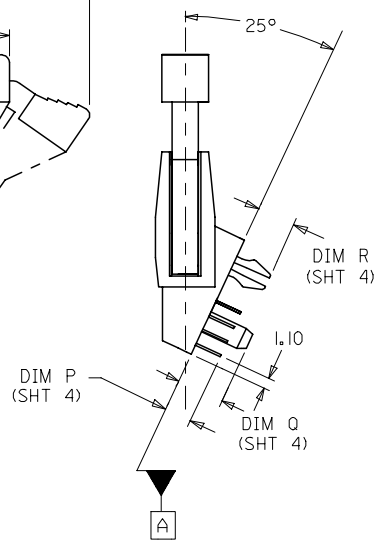
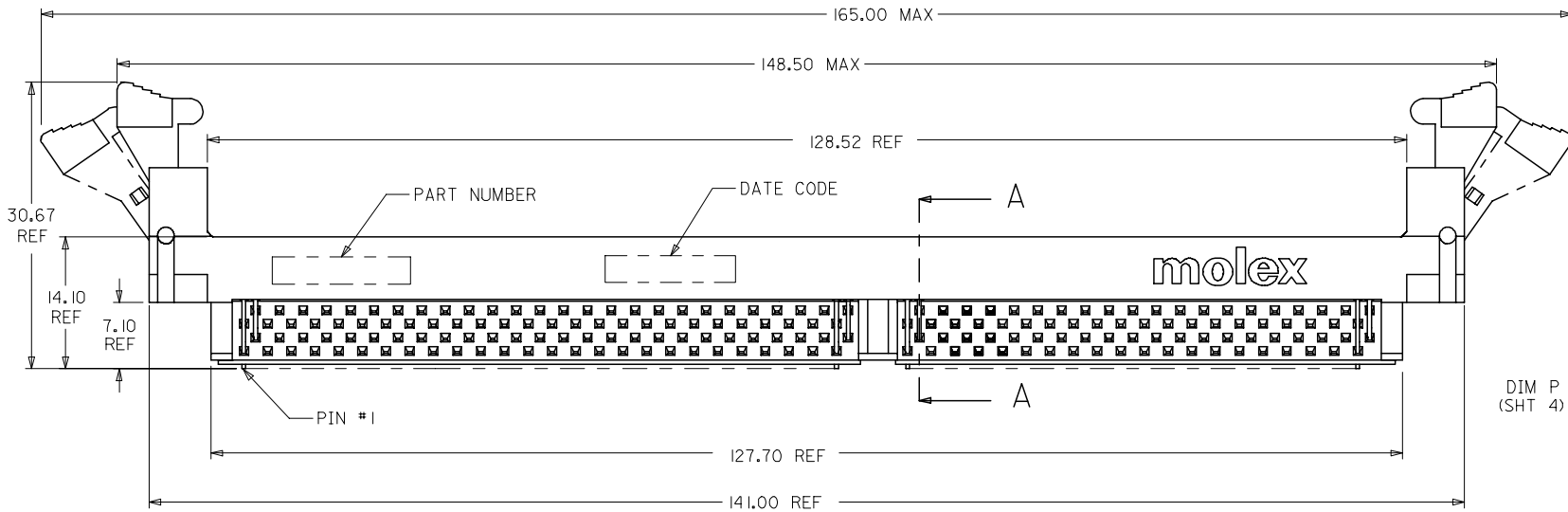
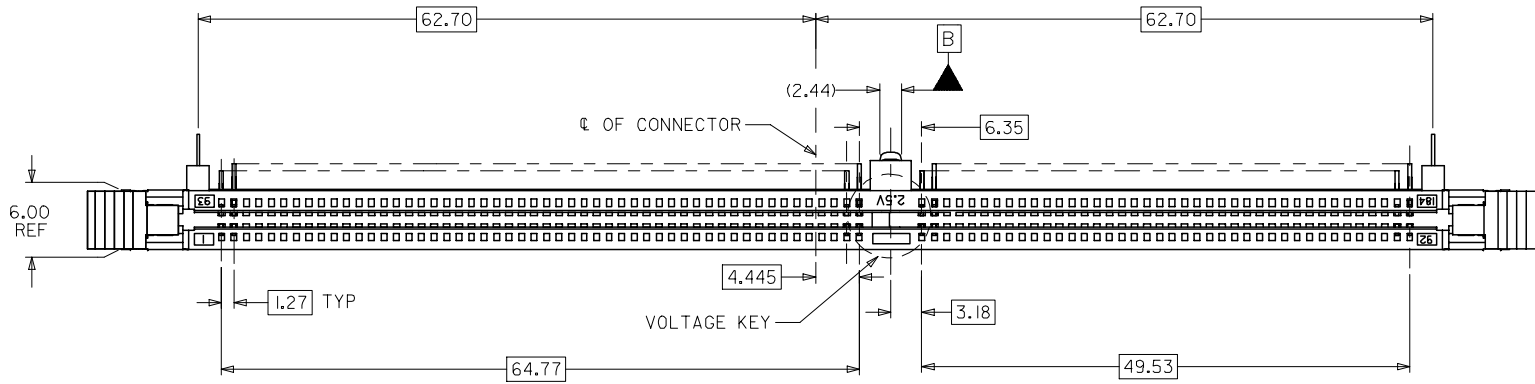
**Mates With**

JEDEC MO-206 modules

This document was generated on 04/09/2010

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10 9 8 7 6 5 4 3 2 1



- NOTES:
- MATERIALS: HOUSING & BASEPLATE - LCP, GLASS FILLED, UL 94V-0, COLOR: BLACK  
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0, COLOR: BEIGE  
TERMINAL AND FORKLOCK - COPPER ALLOY
  - FINISHES: CONTACT AREA: SEE TABLE ON SHEET 4  
SOLDER TAILS: 2.54µm/100µ" MIN. TIN  
OVER 1.27mm/50µ" MIN. NICKEL
  - PRODUCT SPECIFICATIONS: PS-87623-002 FOR PERFORMANCE SPECIFICATIONS.
  - DATE CODE SHALL BE MARKED LEGIBLY AS SHOWN: XX XX  
YEAR — WEEK
  - PART NUMBER SHALL BE MARKED LEGIBLY AS SHOWN: 87623-0XXX  
REFER TO TABLE

OBS TIN/LEAD P/N	EC NO: S2006-0734	2006/02/27	QUALITY SYMBOLS
	DRWN:MLG	2006/02/28	
	CHKD:HO	2006/03/01	
	APPR:GJLEE		
REV	DESCRIPTION		

QUALITY SYMBOLS	▽=0	
	▽=0	
GENERAL TOLERANCES (UNLESS SPECIFIED)		
	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

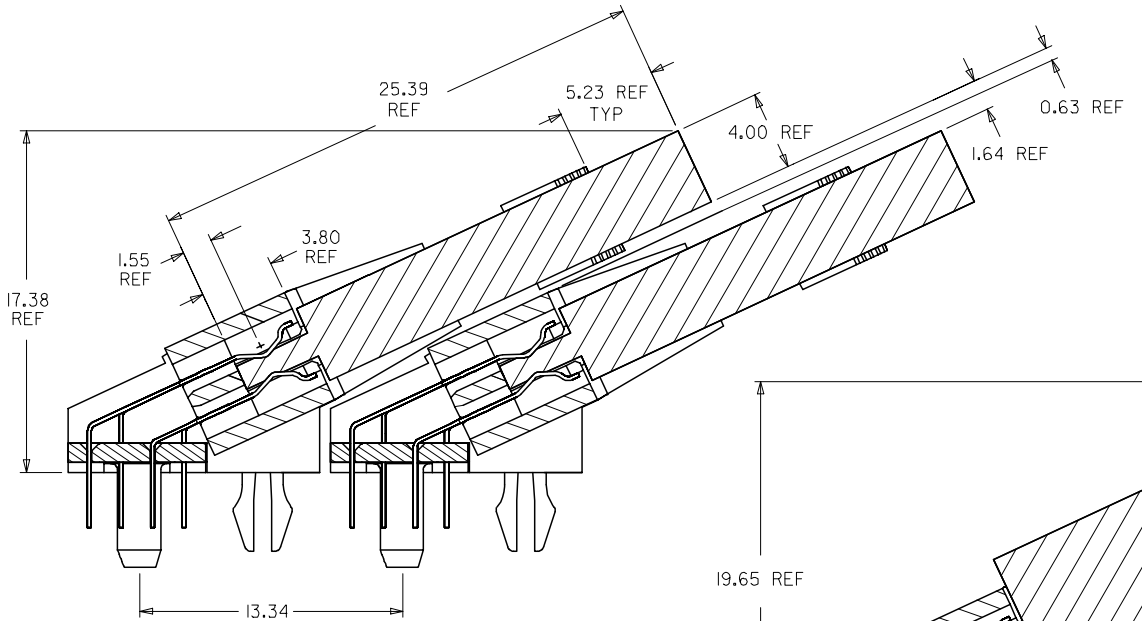
DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
LPL IM	2000/01/10
CHECKED BY	DATE
DSOH	2000/02/02
APPROVED BY	DATE
SKTOH	2000/02/02
MATERIAL NO.	
SEE TABLE	
SIZE	A3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	
TITLE		
DDR DIMM, 1.27MM PITCH		
184 CKTS, 25 DEG.		
MOLEX MOLEX INCORPORATED		
MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE TABLE	SD-87623-001	1 OF 4

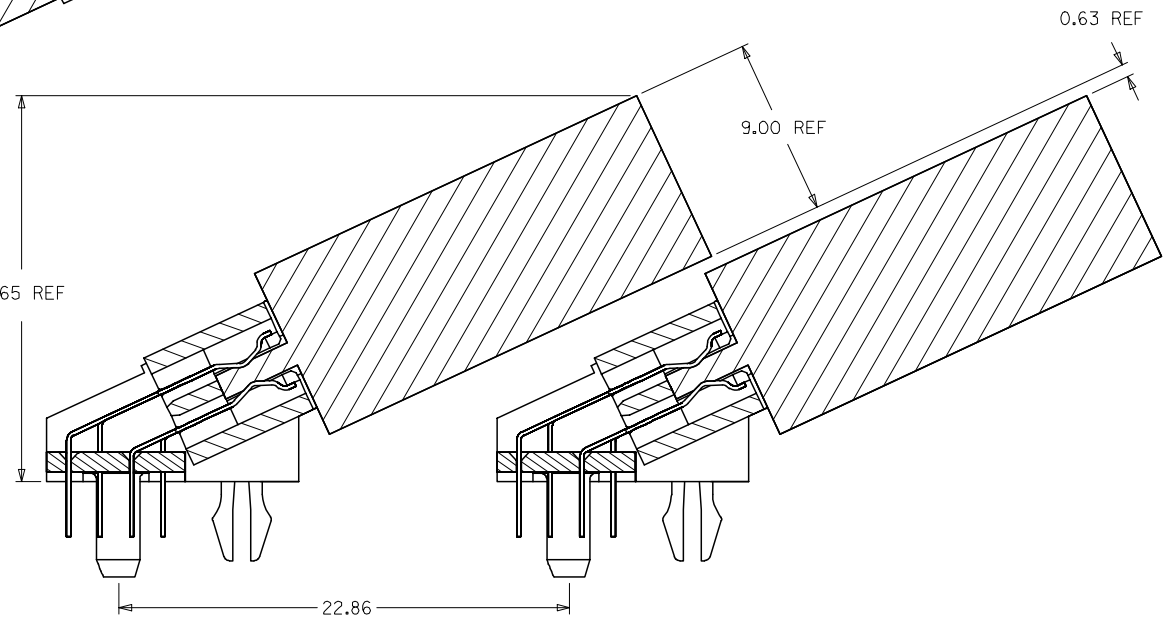
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10 9 8 7 6 5 4 3 2 1

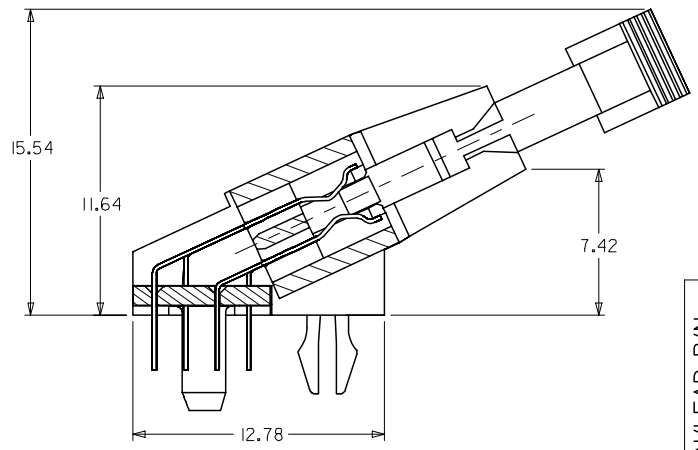
F  
E  
D  
C  
B  
A



MINIMUM RECOMMENDED ROW TO ROW SPACING  
WHEN USING A 4.00 mm THICK  
MODULE (TYPICAL TSOP PACKAGING)



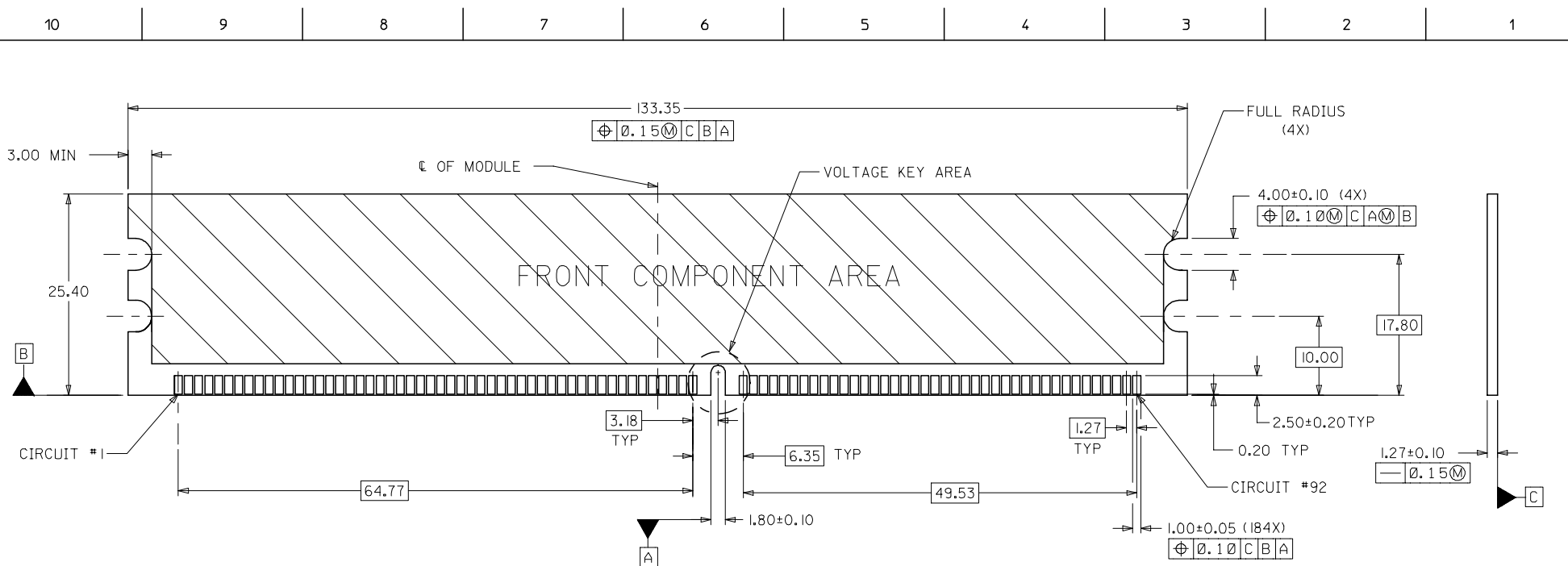
MINIMUM RECOMMENDED ROW TO ROW SPACING  
WHEN USING A 9.00 mm THICK  
MODULE (TYPICAL SOJ PACKAGING)



SECTION A-A

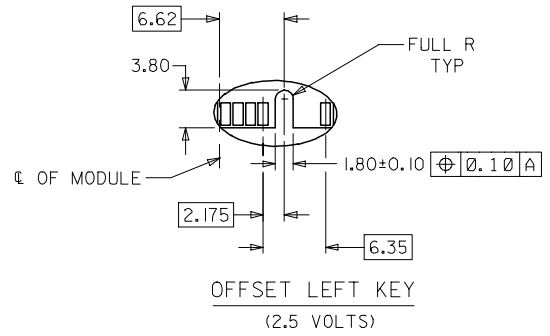
OBS TIN/LEAD P/N EC NO: S2006-0734 DRWN:MLONG CHKD:IHO APPR:GJLEE	2006/02/27	QUALITY SYMBOLS ▽=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	2006/02/28		4 PLACES ± ---	± ---	DRAWN BY LPL IM	DATE 2000/01/10	TITLE DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.			
	2006/03/01		3 PLACES ± ---	± ---	CHECKED BY DSOH	DATE 2000/02/02	APPROVED BY SKTOH			
			2 PLACES ± 0.25	± ---	APPROVED BY DATE 2000/02/02	MATERIAL NO. DOCUMENT NO. SD-87623-001				
		1 PLACE ± ---	± ---	ANGULAR ± 5 °		SEE TABLE		MOLEX INCORPORATED		SHEET NO. 2 OF 4
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1



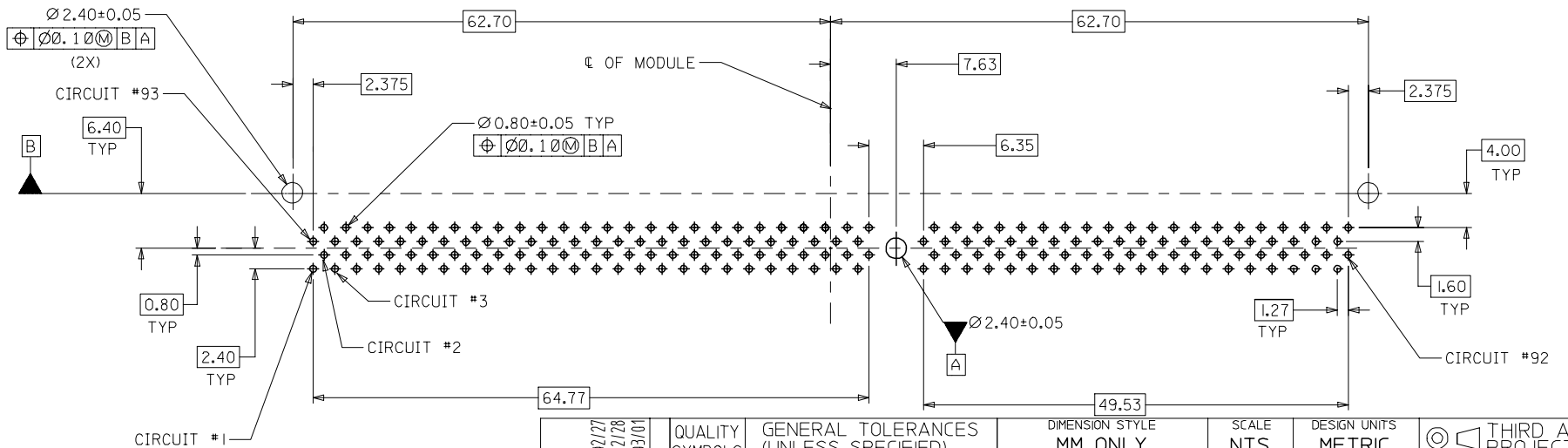
RECOMMENDED MODULE LAYOUT  
 (PER JEDEC STANDARD MO-206, 184 CKT.)  
 UNLESS OTHERWISE SPECIFIED, GENERAL TOLERANCE FOR MODULE = ±0.13

VOLTAGE KEY AREA



OBS TIN/LEAD P/N EC NO: S2006-0734 DRWN:MLONG CHKD:HO APPR:GGLLEE	2006/02/27	QUALITY SYMBOLS ▽=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	2006/02/28		mm	INCH	DRAWN BY LPL IM		DATE 2000/01/10			
	2006/03/01		4 PLACES ±---	±---	CHECKED BY DSOH		DATE 2000/02/02		TITLE DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.	
			3 PLACES ±---	±---	APPROVED BY SKTOH		DATE 2000/02/02		MOLEX INCORPORATED	
			2 PLACES ±0.25	±---	MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
			1 PLACE ±---	±---	SEE TABLE		SD-87623-001		3 OF 4	
			ANGULAR ± 5 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

PART NUMBER	VOLTAGE KEY	CKT SIZE	TAIL LENGTH P±0.25	PEG LENGTH 0±0.25	FORK LENGTH R±0.25	RECOMMENDED PCB THICKNESS	FINISHES: CONTACT AREA
87623-2001	LEFT (2.5V)	184	2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.38µM/15µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL
87623-2011			3.18	4.83	3.94		
87623-2012			3.18	3.18	3.18		
87623-2013			3.81	4.83	4.42	2.84	
87623-2101			2.79	3.18	3.18	1.57	
87623-2111			3.18	4.83	3.94		
87623-2113			3.81	4.83	4.42		
87623-2115			3.18	3.18	3.18	1.57	SELECTIVE GOLD 0.76µM/30µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL



RECOMMENDED  
P.C. BOARD HOLE PATTERN  
(CONNECTOR SIDE)

OBS TIN/LEAD P/N  
EC NO: S2006-0734  
DRWN:HLONG  
CHKD:HO  
APPR:GJLEE

QUALITY SYMBOLS  
▽=0  
△=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ± 5 °		

DRAFT WHERE APPLICABLE  
MUST REMAIN  
WITHIN DIMENSIONS

DIMENSION STYLE  
MM ONLY

DRAWN BY	DATE
LPL IM	2000/01/10
CHECKED BY	DATE
DSOH	2000/02/02
APPROVED BY	DATE
SKTOH	2000/02/02

MATERIAL NO. SEE TABLE

SCALE NTS  
DESIGN UNITS METRIC  
THIRD ANGLE PROJECTION

TITLE  
DDR DIMM, 1.27MM PITCH  
184 CKTS, 25 DEG.

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DOCUMENT NO. SD-87623-001  
SHEET NO. 4 OF 4

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